

PAT-NO: JP02000299243A
DOCUMENT-IDENTIFIER: JP 2000299243 A
TITLE: LAMINATED CHIP TYPE ELECTRONIC COMPONENT
PUEN-DATE: October 24, 2000

INVENTOR-INFORMATION:

NAME	COUNTRY
AIBA, TAKASHI	N/A
OCHIAI, TOSHIKI	N/A
MARUNO, TETSUJI	N/A

ASSIGNEE-INFORMATION:

NAME	COUNTRY
TDK CORP	N/A

APPL-NO: JP11108846
APPL-DATE: April 16, 1999

INT-CL (IPC): H01G004/12, C23C030/00

ABSTRACT:

PROBLEM TO BE SOLVED: To prevent the oxidation of external electrodes and obtain satisfactory electrical conduction by forming main electrode layers electrically connected to internal electrodes of a sintered metal consisting essentially of copper or nickel and arranging the external electrodes whose outer surfaces are covered with plated layers made of a noble metal which is hard to oxidize.

SOLUTION: A laminated chip capacitor is fabricated by forming a green sheet from a dielectric material containing barium titanate, and forming an internal electrode 10 of a base metal such as nickel. Using a capacitor chip element

assembly 11, which is formed by sintering a plurality of internal electrodes 10 and ceramic sheets alternately laminated one upon another as a substrate, the assembly 11 is provided at both ends thereof with external electrodes 12 electrically connected to the electrodes 10. The electrodes 12 have main electrode layers 12a formed of a sintered metal which is obtained by coating conductive paste, which consists mainly of copper or nickel, to both ends of the assembly 11 and sintering the conductive paste. The layers 12a are electrically connected to the electrodes 10. The outer surface of each electrode 12 is covered with an electroplated layer 12c made of a noble metal such as silver or gold which is hard to be oxidized.

COPYRIGHT: (C)2000,JPO